

Voltage Detector IC Series

Free Delay Time Setting CMOS Voltage Detector IC Series


BD52□□G, BD52□□FVE, BD53□□G, BD53□□FVE series

No.09006EBT03

● Description

ROHM's BD52□□G/FVE and BD53□□G/FVE series are highly accurate, low current consumption reset IC series with a built-in delay circuit. The lineup was established with tow output types (Nch open drain and CMOS output) and detection voltages range from 2.3V to 6.0V in increments of 0.1V, so that the series may be selected according the application at hand.

● Features

- 1) Detection voltage: 2.3V to 6.0V (Typ.), 0.1V steps
- 2) High accuracy detection voltage: $\pm 1.0\%$
- 3) Ultra-low current consumption: 0.8 μ A (Typ.)
- 4) Nch open drain output (BD52□□G/FVE), CMOS output (BD53□□G/FVE)
- 5) Compact packages VSOF5: BD52□□FVE, BD53□□FVE
 SSOP5: BD52□□G, BD53□□G

● Applications

All electronic devices that use micro controllers and logic circuits

● Selection Guide

Part Number : BD5

①
②
③

No.	Specifications	Description
①	Output Circuit Format	2:Open Drain Output, 3:CMOS Output
②	Detection Voltage	Example: Displays VS over a 2.3V to 6.0V range in 0.1V increments.
③	Package	G:SSOP5 / FVE:VSOF5

● Lineup

Marking	Detection Voltage	Part Number	Marking	Detection Voltage	Part Number	Marking	Detection Voltage	Part Number	Marking	Detection Voltage	Part Number
PW	6.0V	BD5260	PB	4.1V	BD5241	RW	6.0V	BD5360	RB	4.1V	BD5341
PV	5.9V	BD5259	PA	4.0V	BD5240	RV	5.9V	BD5359	RA	4.0V	BD5340
PU	5.8V	BD5258	MV	3.9V	BD5239	RU	5.8V	BD5358	QV	3.9V	BD5339
PT	5.7V	BD5257	MU	3.8V	BD5238	RT	5.7V	BD5357	QU	3.8V	BD5338
PS	5.6V	BD5256	MT	3.7V	BD5237	RS	5.6V	BD5356	QT	3.7V	BD5337
PR	5.5V	BD5255	MS	3.6V	BD5236	RR	5.5V	BD5355	QS	3.6V	BD5336
PQ	5.4V	BD5254	MR	3.5V	BD5235	RQ	5.4V	BD5354	QR	3.5V	BD5335
PP	5.3V	BD5253	MQ	3.4V	BD5234	RP	5.3V	BD5353	QQ	3.4V	BD5334
PN	5.2V	BD5252	MP	3.3V	BD5233	RN	5.2V	BD5352	QP	3.3V	BD5333
PM	5.1V	BD5251	MN	3.2V	BD5232	RM	5.1V	BD5351	QN	3.2V	BD5332
PL	5.0V	BD5250	MM	3.1V	BD5231	RL	5.0V	BD5350	QM	3.1V	BD5331
PK	4.9V	BD5249	ML	3.0V	BD5230	RK	4.9V	BD5349	QL	3.0V	BD5330
PJ	4.8V	BD5248	MK	2.9V	BD5229	RJ	4.8V	BD5348	QK	2.9V	BD5329
PH	4.7V	BD5247	MJ	2.8V	BD5228	RH	4.7V	BD5347	QJ	2.8V	BD5328
PG	4.6V	BD5246	MH	2.7V	BD5227	RG	4.6V	BD5346	QH	2.7V	BD5327
PF	4.5V	BD5245	MG	2.6V	BD5226	RF	4.5V	BD5345	QG	2.6V	BD5326
PE	4.4V	BD5244	MF	2.5V	BD5225	RE	4.4V	BD5344	QF	2.5V	BD5325
PD	4.3V	BD5243	ME	2.4V	BD5224	RD	4.3V	BD5343	QE	2.4V	BD5324
PC	4.2V	BD5242	MD	2.3V	BD5223	RC	4.2V	BD5342	QD	2.3V	BD5323

● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Power Supply Voltage		VDD-GND	-0.3 ~ +10	V
Output Voltage	Nch Open Drain Output	VOUT	GND-0.3 ~ +10	V
	CMOS Output		GND-0.3 ~ VDD+0.3	
Power Dissipation	SSOP5 ^{*1*3}	Pd	540	mW
	VSO5 ^{*2*3}		210	
Operating Temperature		Topr	-40 ~ +105	°C
Ambient Storage Temperature		Tstg	-55 ~ +125	°C

*1 Use above Ta=25°C results in a 5.4mW loss per degree.

*2 Use above Ta=25°C results in a 2.1mW loss per degree.

*3 When a ROHM standard circuit board (70mm×70mm×1.6mm glass epoxy board) is mounted.

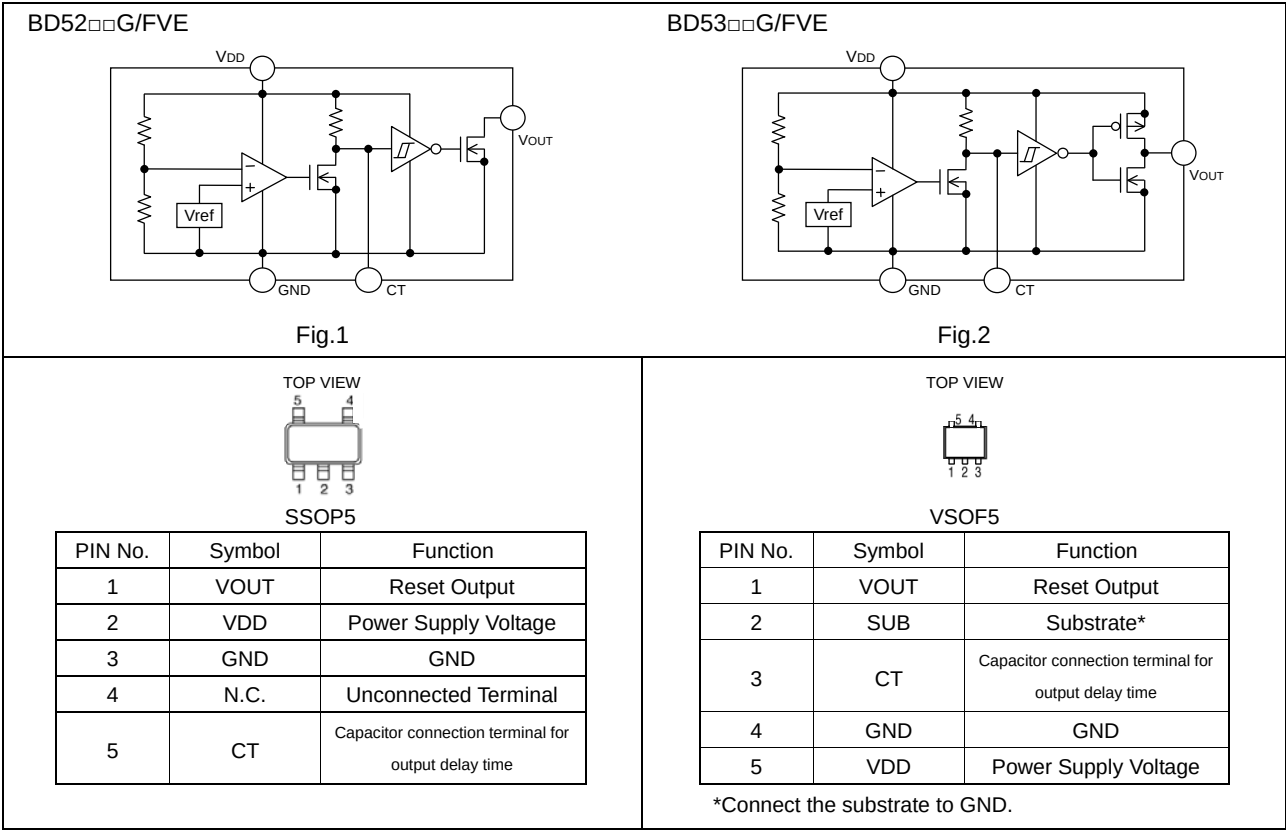
● Electrical characteristics (Unless Otherwise Specified Ta=-40 to 105°C)

Parameter	Symbol	Condition		Limit			Unit
				Min.	Typ.	Max.	
Detection Voltage	V _{DET}	VDD=H→L, R _L =470kΩ ^{*1}		V _{DET} (T) ×0.99	V _{DET} (T)	V _{DET} (T) ×1.01	V
Circuit Current when ON	I _{DD1}	VDD=V _{DET} -0.2V	V _{DET} =2.3-3.1V	-	0.80	2.40	μA
			V _{DET} =3.2-4.2V	-	0.85	2.55	
			V _{DET} =4.3-5.2V	-	0.90	2.70	
			V _{DET} =5.3-6.0V	-	0.95	2.85	
Circuit Current when OFF	I _{DD2}	VDD=V _{DET} +2.0V	V _{DET} =2.3-3.1V	-	0.75	2.25	μA
			V _{DET} =3.2-4.2V	-	0.80	2.40	
			V _{DET} =4.3-5.2V	-	0.85	2.55	
			V _{DET} =5.3-6.0V	-	0.90	2.70	
Operating Voltage Range	V _{OPL}	V _{OL} ≤0.4V, Ta=25~105°C, R _L =470kΩ		0.95	-	-	V
		V _{OL} ≤0.4V, Ta=-40~25°C, R _L =470kΩ		1.20	-	-	
'Low' Output Current (Nch)	I _{OL}	V _{DS} =0.5V VDD=1.2V		0.4	1.2	-	mA
		V _{DS} =0.5V VDD=2.4V		2.0	5.0	-	
'High' Output Current (Pch)	I _{OH}	V _{DS} =0.5V VDD=4.8V V _{DET} =2.3-4.2V		0.7	1.4	-	mA
		V _{DS} =0.5V VDD=6.0V V _{DET} =4.3-5.2V		0.9	1.8	-	
		V _{DS} =0.5V VDD=8.0V V _{DET} =5.3-6.0V		1.1	2.2	-	
Leak Current when OFF	I _{leak}	VDD=V _{DS} =10V ^{*1}		-	-	0.1	μA
CT pin Threshold Voltage	V _{CTH}	VDD=V _{DET} ×1.1, V _{DET} =2.3-2.6V, R _L =470kΩ		VDD ×0.30	VDD ×0.40	VDD ×0.60	V
		VDD=V _{DET} ×1.1, V _{DET} =2.7-4.2V, R _L =470kΩ		VDD ×0.30	VDD ×0.45	VDD ×0.60	
		VDD=V _{DET} ×1.1, V _{DET} =4.3-5.2V, R _L =470kΩ		VDD ×0.35	VDD ×0.50	VDD ×0.60	
		VDD=V _{DET} ×1.1, V _{DET} =5.3-6.0V, R _L =470kΩ		VDD ×0.40	VDD ×0.50	VDD ×0.60	
Output Delay Resistance	R _{CT}	VDD=V _{DET} ×1.1 V _{CT} =0.5V ^{*1}		5.5	9	12.5	MΩ
CT pin Output Current	I _{CT}	V _{CT} =0.1V VDD=0.95V ^{*1}		15	40	-	μA
		V _{CT} =0.5V VDD=1.5V		150	240	-	
Detection Voltage Temperature coefficient	V _{DET} /ΔT	Ta=-40°C to 105°C		-	±100	±360	ppm/°C
Hysteresis Voltage	ΔV _S	VDD=L→H→L, R _L =470kΩ		V _{DET} ×0.03	V _{DET} ×0.05	V _{DET} ×0.08	V

V_S(T) : Standard Detection Voltage (2.3V to 6.0V, 0.1V step)R_L : Pull-up resistor to be connected between Vout and power supply.
Designed Guarantee. (Outgoing inspection is not done on all products.)

*1 Guarantee is Ta=25°C.

● Block Diagrams



● Reference Data (Unless specified otherwise, $T_a=25^\circ\text{C}$)

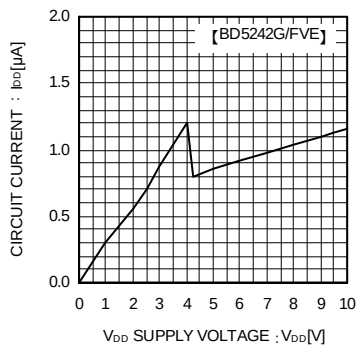


Fig.3 Circuit Current

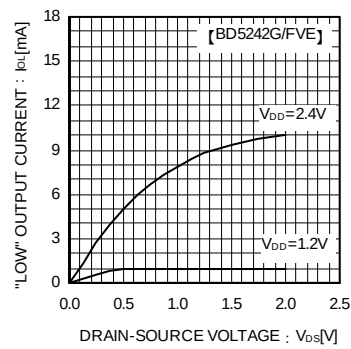


Fig.4 "Low" Output Current

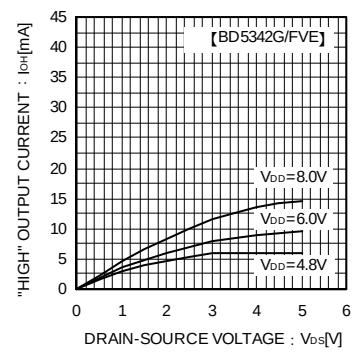


Fig.5 "High" Output Current

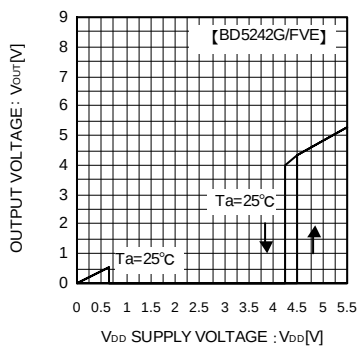


Fig.6 I/O Characteristics

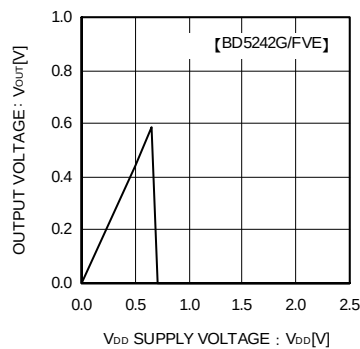


Fig.7 Operating Limit Voltage

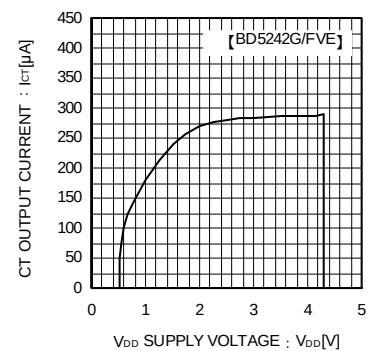


Fig.8 CT Terminal Current

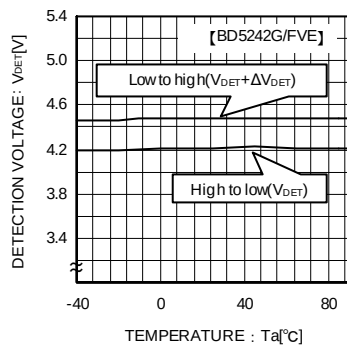


Fig.9 Detection Voltage Release Voltage

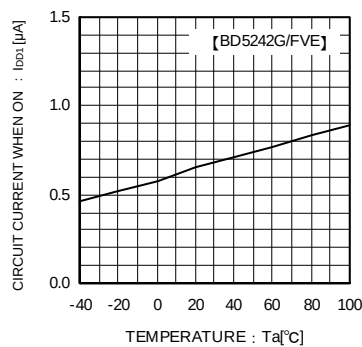


Fig.10 Circuit Current when ON

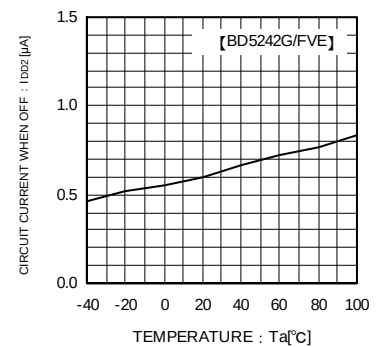


Fig.11 Circuit Current when OFF

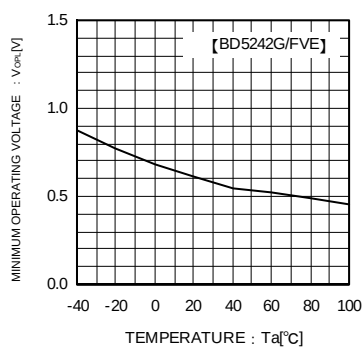


Fig.12 Operating Limit Voltage

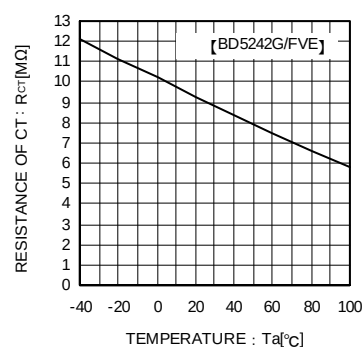
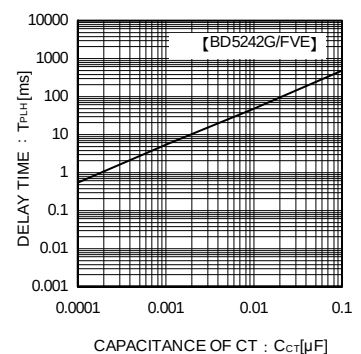


Fig.13 Ct Terminal Circuit Resistance

Fig.14 Delay Time (T_{PLH}) and CT Terminal External Capacitance

● Setting of Detector Delay Time

This detector IC can be set delay time at the rise of V_{DD} by the capacitor connected to CT terminal.

Delay time at the rise of V_{DD} T_{PLH} : Time until when V_{OUT} rise to 1/2 of V_{DD} after V_{DD} rise up and beyond the release voltage ($V_{DET} + \Delta V_{DET}$)

$$T_{PLH} = -C_{CT} \times R_{CT} \times \ln \left(\frac{V_{DD} - V_{CTH}}{V_{DD}} \right)$$

C_{CT} : CT pin Externally Attached Capacitance

V_{CTH} : CT pin Threshold Voltage (P.2 V_{CTH} refer.)

R_{CT} : CT pin Internal Impedance (P.2 R_{CT} refer.)

$\ln$: Natural Logarithm

● Reference Data of Falling Time (T_{PHL}) Output

Examples of Falling Time (T_{PHL}) Output

Part Number	$t_{PHL}[\mu s]$ -40°C	$t_{PHL}[\mu s]$,+25°C	$t_{PHL}[\mu s]$,+105°C
BD5227G	30.8	30	28.8
BD5327G	26.8	26	24.8

*This data is for reference only.

The figures will vary with the application, so please confirm actual operating conditions before use.

● Explanation of Operation

For both the open drain type (Fig.15) and the CMOS output type (Fig.16), the detection and release voltages are used as threshold voltages. When the voltage applied to the V_{DD} pins reaches the applicable threshold voltage, the V_{OUT} terminal voltage switches from either "High" to "Low" or from "Low" to "High". Because the BD52□□G/FVE series uses an open drain output type, it is possible to connect a pull-up resistor to V_{DD} or another power supply [The output "High" voltage (V_{OUT}) in this case becomes V_{DD} or the voltage of the other power supply].

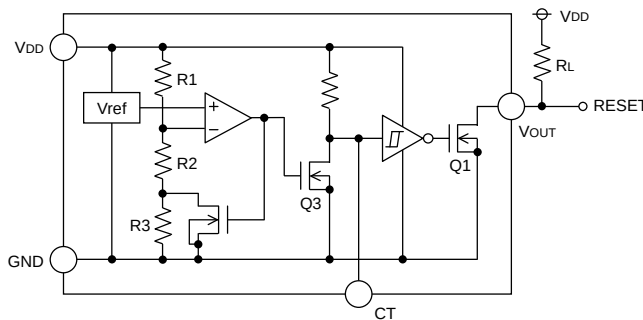


Fig.15 (BD52□□ Type Internal Block Diagram)

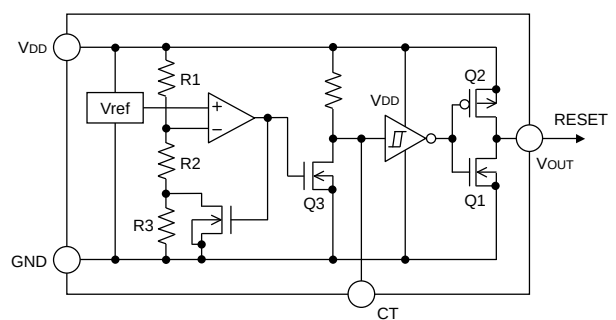


Fig.16 (BD53□□ Type Internal Block Diagram)

● Timing Waveforms

Example: the following shows the relationship between the input voltage V_{DD} , the CT Terminal Voltage V_{CT} and the output voltage V_{OUT} when the input power supply voltage V_{DD} is made to sweep up and sweep down (The circuits are those in Fig.15 and 16).

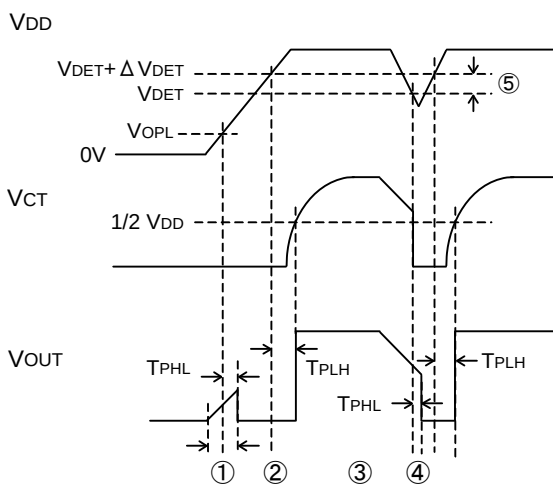


Fig.17

① When the power supply is turned on, the output is unsettled from after over the operating limit voltage (V_{OPL}) until T_{PHL} . Therefore it is possible that the reset signal is not outputted when the rise time of V_{DD} is faster than T_{PHL} .

② When V_{DD} is greater than V_{OPL} but less than the reset release voltage ($V_{DET} + \Delta V_{DET}$), the CT terminal (V_{CT}) and output (V_{OUT}) voltages will switch to L.

③ If V_{DD} exceeds the reset release voltage ($V_{DET} + \Delta V_{DET}$), then V_{OUT} switches from L to H (with a delay to the CT terminal).

④ If V_{DD} drops below the detection voltage (V_{DET}) when the power supply is powered down or when there is a power supply fluctuation, V_{OUT} switches to L (with a delay of T_{PHL}).

⑤ The potential difference between the detection voltage and the release voltage is known as the hysteresis width (ΔV_{DET}). The system is designed such that the output does not flip-flop with power supply fluctuations within this hysteresis width, preventing malfunctions due to noise.

● Circuit Applications

1) Examples of a common power supply detection reset circuit

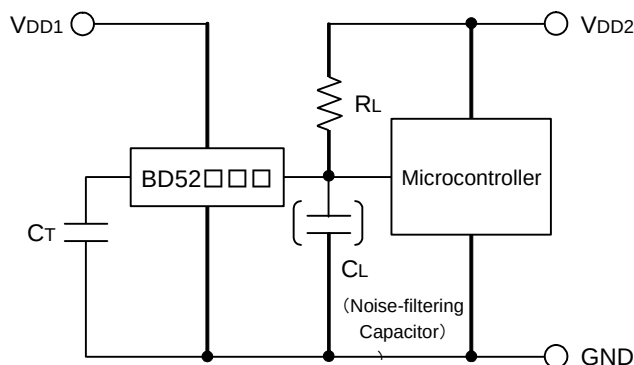


Fig.18 Open Collector Output Type

Application examples of BD52□□G/FVE series (Open Drain output type) and BD53□□G/FVE series (CMOS output type) are shown below.

CASE1: the power supply of the microcontroller (VDD2) differs from the power supply of the reset detection (VDD1).

Use the open drain output type (BD52□□G/FVE) attached a load resistance (RL) between the output and VDD2. (As shown Fig.15)

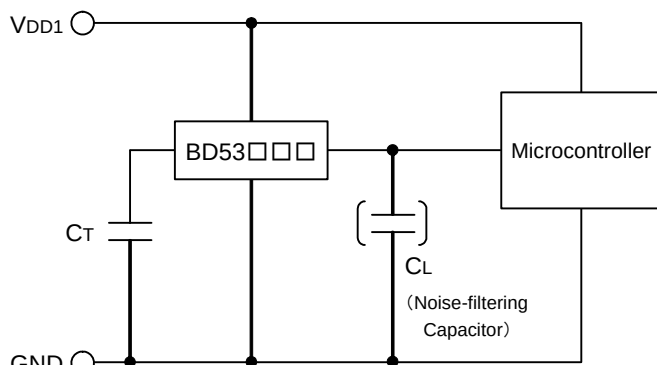


Fig.19 CMOS Output Type

CASE2: the power supply of the microcontroller (VDD1) is same as the power supply of the reset detection (VDD1).

Use CMOS output type (BD53□□G/FVE) or open drain output type (BD52□□G/FVE) attached a load resistance (RL) between the output and VDD1. (As shown Fig.16)

When a capacitance CL for noise filtering is connected to the VOUT pin (the reset signal input terminal of the microcontroller), please take into account the waveform of the rise and fall of the output voltage (VOUT).

2) The following is an example of a circuit application in which an OR connection between two types of detection voltages resets the microcontroller.

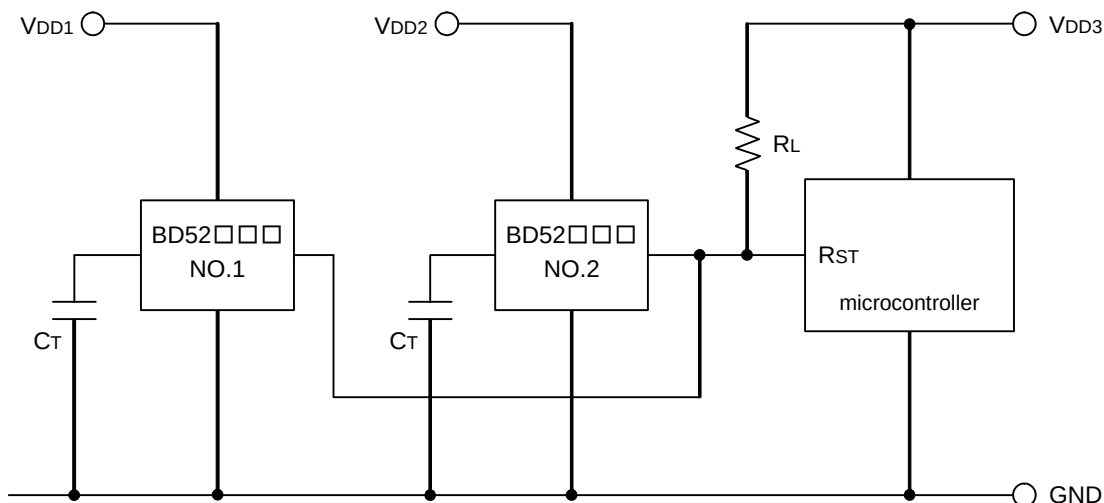


Fig.20

When there are many power supplies of the system, power supplies VDD1 and VDD2 are being monitored separately, and it is necessary to reset the microcomputer, it is possible to use an OR connection on the open drain output type BD52□□G/FVE series to pull-up to the desired voltage (VDD3) as shown in Fig.17 and make the output "High" voltage matches the power supply voltage VDD3 of the microcontroller.

3) Examples of the power supply with resistor dividers

In applications where the power supply input terminal (VDD) of an IC with resistor dividers, it is possible that a through current will momentarily flow into the circuit when the output logic switches, resulting in malfunctions (such as output oscillatory state).

(Through-current is a current that momentarily flows from the power supply (VDD) to ground (GND) when the output level switches from "High" to "Low" or vice versa.)

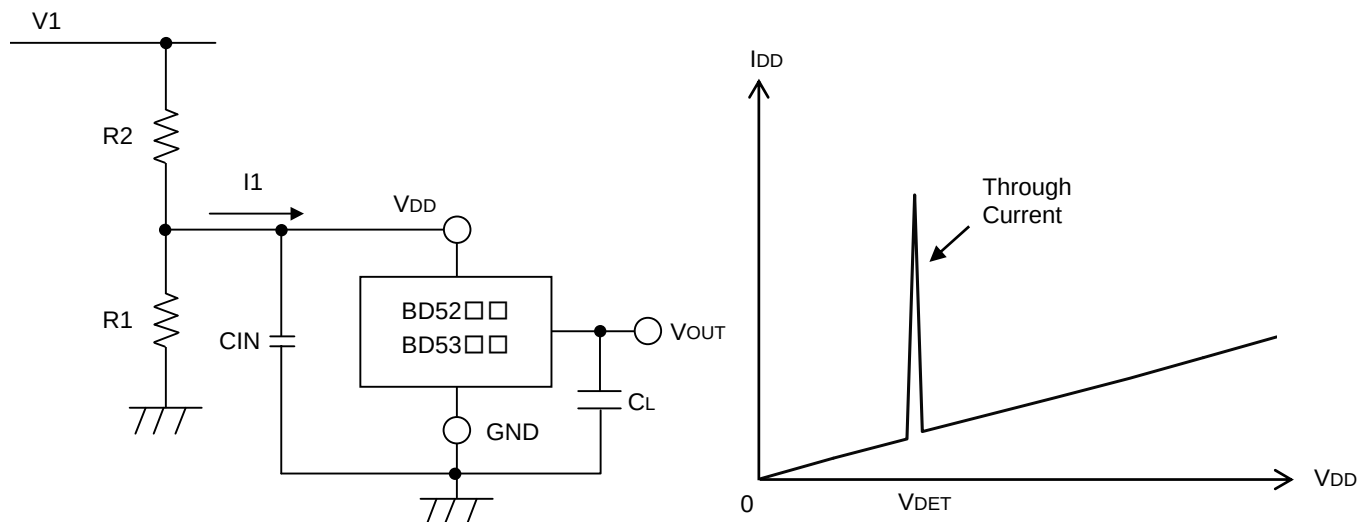


Fig.21

A voltage drop of [the through-current (I_1) $\times$ [input resistor (R_2)] is caused by the through current, and the input voltage to descends, when the output switches from "Low" to "High". When the input voltage decreases and falls below the detection voltage, the output voltage switches from "High" to "Low". At this time, the through-current stops flowing through output "Low", and the voltage drop is eliminated. As a result, the output switches from "Low" to "High", which again causes the through current to flow and the voltage drop. This process is repeated, resulting in oscillation.

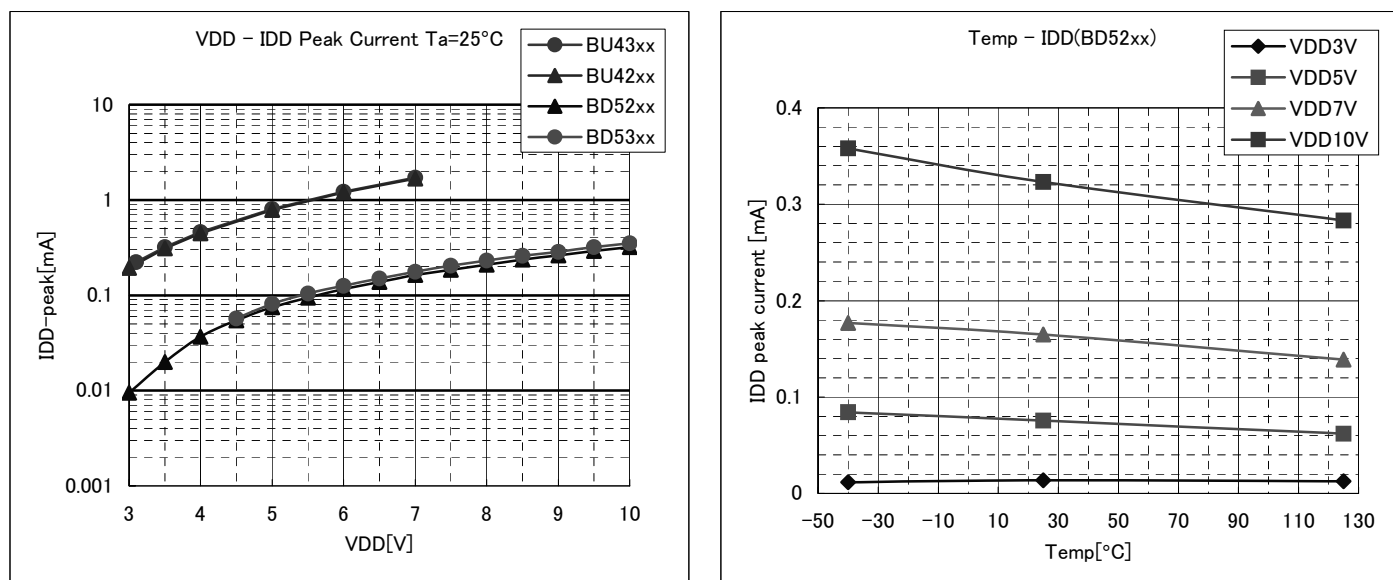


Fig.22 Current Consumption vs. Power Supply Voltage

*This data is for reference only.

The figures will vary with the application, so please confirm actual operating conditions before use.

● Operation Notes**1 . Absolute maximum range**

Absolute Maximum Ratings are those values beyond which the life of a device may be destroyed. We cannot be defined the failure mode, such as short mode or open mode. Therefore a physical security countermeasure, like fuse, is to be given when a specific mode to be beyond absolute maximum ratings is considered.

2 . GND potential

GND terminal should be a lowest voltage potential every state.

Please make sure all pins, which are over ground even if, include transient feature.

3 . Electrical Characteristics

Be sure to check the electrical characteristics that are one the tentative specification will be changed by temperature, supply voltage, and external circuit.

4 . Bypass Capacitor for Noise Rejection

Please put into the capacitor of 1 μ F or more between VDD pin and GND, and the capacitor of about 1000pF between VOUT pin and GND, to reject noise. If extremely big capacitor is used, transient response might be late. Please confirm sufficiently for the point.

5 . Short Circuit between Terminal and Soldering

Don't short-circuit between Output pin and VDD pin, Output pin and GND pin, or VDD pin and GND pin. When soldering the IC on circuit board, please be unusually cautious about the orientation and the position of the IC. When the orientation is mistaken the IC may be destroyed.

6 . Electromagnetic Field

Mal-function may happen when the device is used in the strong electromagnetic field.

7 . The VDD line impedance might cause oscillation because of the detection current.**8 . A VDD -GND capacitor (as close connection as possible) should be used in high VDD line impedance condition.****9 . Lower than the minimum input voltage makes the VOUT high impedance, and it must be VDD in pull up (VDD) condition.****10 . This IC has extremely high impedance terminals. Small leak current due to the uncleanness of PCB surface might cause unexpected operations. Application values in these conditions should be selected carefully. If the leakage is assumed between the VOUT terminal and the GND terminal, the pull-up resistor should be less than 1/10 of the assumed leak resistance. If 10M Ω leakage is assumed between the CT terminal and the GND terminal, 1M Ω connection between the CT terminal and the VDD terminal would be recommended. The value of RCT depends on the external resistor that is connected to CT terminal, so please consider the delay time that is decided by $\tau \times RCT \times CCT$ changes.****11. External parameters**

The recommended parameter range for CT is 100pF~0.1 μ F and RL is 50k Ω ~1M Ω . There are many factors (board layout, etc) that can affect characteristics. Please verify and confirm using practical applications.

12. Power on reset operation

Please note that the power on reset output varies with the VDD rise up time. Please verify the actual operation.

13. Precautions for board inspection

Connecting low-impedance capacitors to run inspections with the board may produce stress on the IC. Therefore, be certain to use proper discharge procedure before each process of the test operation.

To prevent electrostatic accumulation and discharge in the assembly process, thoroughly ground yourself and any equipment that could sustain ESD damage, and continue observing ESD-prevention procedures in all handling, transfer and storage operations. Before attempting to connect components to the test setup, make certain that the power supply is OFF. Likewise, be sure the power supply is OFF before removing any component connected to the test setup.

14. When the power supply, is turned on because of in certain cases, momentary Rash-current flow into the IC at the logic unsettled, the couple capacitance, GND pattern of width and leading line must be considered.

● Part Number Selection

B D 5 2

BD52: Adjustable Delay Time
CMOS Reset IC
Open Drain Type
BD53: Adjustable Delay Time
CMOS Reset IC
CMOS Output Type

2 3

Reset Voltage Value
23: 2.3V to (0.1V step)
60: 6.0V

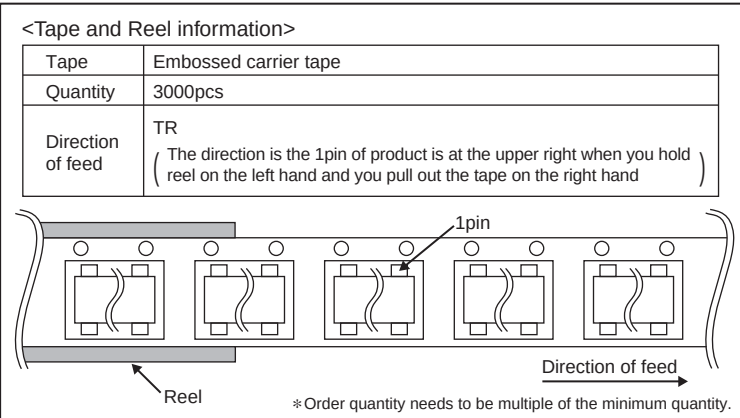
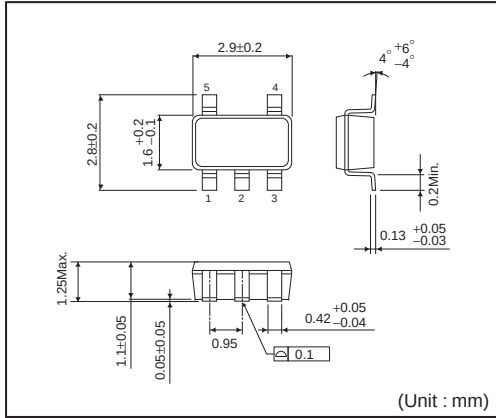
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Package
G: SSOP5
FVE: VSOF5

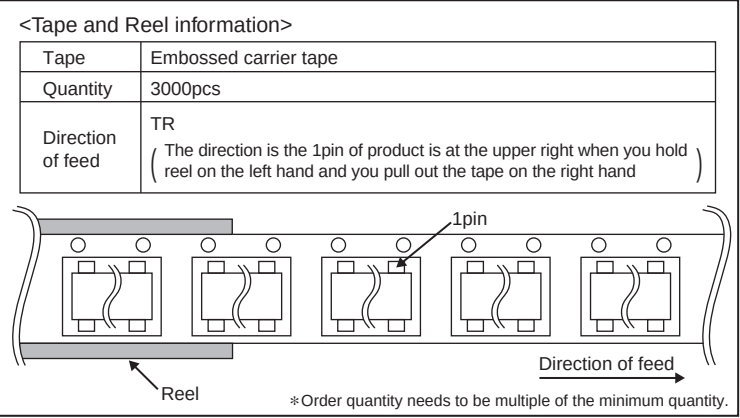
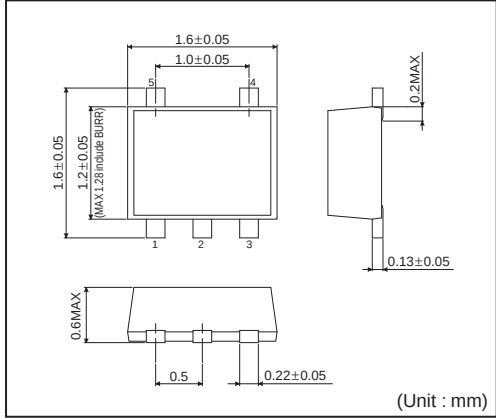
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Taping Specifications
Embossed Taping

SSOP5



VSOF5



Notes

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The Products are not designed or manufactured to be used with any equipment, device or system which requires an extremely high level of reliability the failure or malfunction of which may result in a direct threat to human life or create a risk of human injury (such as a medical instrument, transportation equipment, aerospace machinery, nuclear-reactor controller, fuel-controller or other safety device). ROHM shall bear no responsibility in any way for use of any of the Products for the above special purposes. If a Product is intended to be used for any such special purpose, please contact a ROHM sales representative before purchasing.

If you intend to export or ship overseas any Product or technology specified herein that may be controlled under the Foreign Exchange and the Foreign Trade Law, you will be required to obtain a license or permit under the Law.



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More detail product informations and catalogs are available, please contact us.

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